

INSPECTION CERTIFICATE


TAIYO INK MFG. CO., LTD.

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 QA Group TEL+81-93-644-2733

FLEXFINER-25SA 495E25S

Lot No. 9111317

General Judgment

PASS

Nov. 15. 2019

Items	Test method	Specifications	Result
Appearance	Visual inspection (□100mm)	No difference in hue between lot. No uneven coating, stripe, roll-up wrinkle and pin-hole.	PASS
Resist thickness	Stylus profile measuring system	A-layer:5.0+/-1.0 μm A+B layers:25.0+/-2.0 μm	5.5 μm 24.4 μm
Film width	JIS 1(st) class grade (Just after the Slit)	495.0+/-1.0mm	495mm
Photo sensitivity (Provisional)	On FR-4 base material Step tablet:Kodak No.2 at 210mJ/cm2 on the cover-film PEB(preheat)condition after exposure: 90°C/40min.	Gloss photo sensitivity 3 MIN. Residual photo sensitivity 7 MIN.	No. 4 No. 7
Developability	100°C/25min. after Lamination 1wt% Na2CO3 30°C 0.195MPa (2kg/cm ²) 60sec	No ink residue remains No blister and/or No peeling of solder resist after development	PASS

Remarks: Exposure(Contact Exposure)
 High-pressure mercury short arc lamp
 at 210mJ/cm2 on the cover-film
 PEB(preheat)
 Hot-air convection oven 90°C/40min.
 Post cure
 Hot-air convection oven150°C for 60min.

Pencil hardness	TAIYO Internal Test Method (GIP-011A)	3H or above	3H
Adhesion	TAIYO Internal Test Method (GIP-012A)	100/100	100/100
Solder resistance	TAIYO Internal Test Method (GIP-013B) Use rosin-based flux at 10sec. × 1cycle, 260 ± 5°C	No blister and/or No peeling of solder resist	PASS
Solvent resistance	Immersed in propylene glycol-monomethyl ether acetate at 20°C for 20min.	No blister and/or No peeling of solder resist	PASS

RoHS Compliance

Approved by:

